

# SOT1049-3

plastic, extremely thin quad flat package; no leads; 10 terminals

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	XQFN10
<b>Package type industry code</b>	XQFN10
<b>Package style descriptive code</b>	XQFN (extremely thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	- - -
<b>JEDEC package outline code</b>	MO255
<b>JEITA package outline code</b>	- - -
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	30-3-2011

Table 1. Package summary

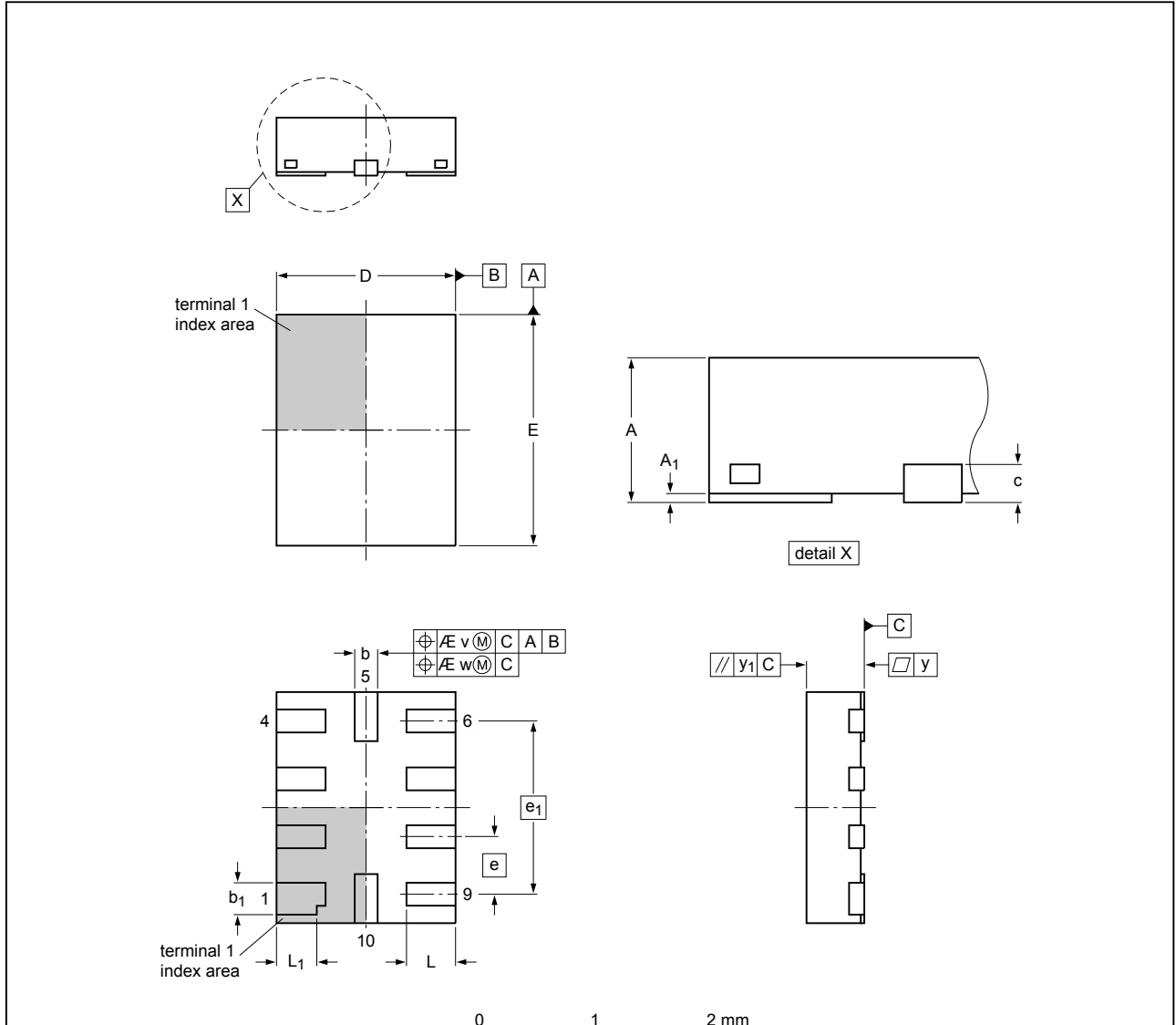
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.45	-	1.55	1.65	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	10	-	



## 2. Package outline

**XQFN10: plastic, extremely thin quad flat package; no leads; 10 terminals; body 1.55 x 2.00 x 0.50 mm**

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**Dimensions**

Unit <sup>(1)</sup>	A	A <sub>1</sub>	b	b <sub>1</sub>	c	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>	v	w	y	y <sub>1</sub>
max	0.5	0.05	0.25	0.33		1.65	2.1			0.48	0.40				
mm nom			0.20	0.28	0.127	1.55	2.0	0.5	1.5	0.43	0.35	0.1	0.05	0.05	0.05
min		0.00	0.15	0.23		1.45	1.9			0.38	0.30				

**Note**

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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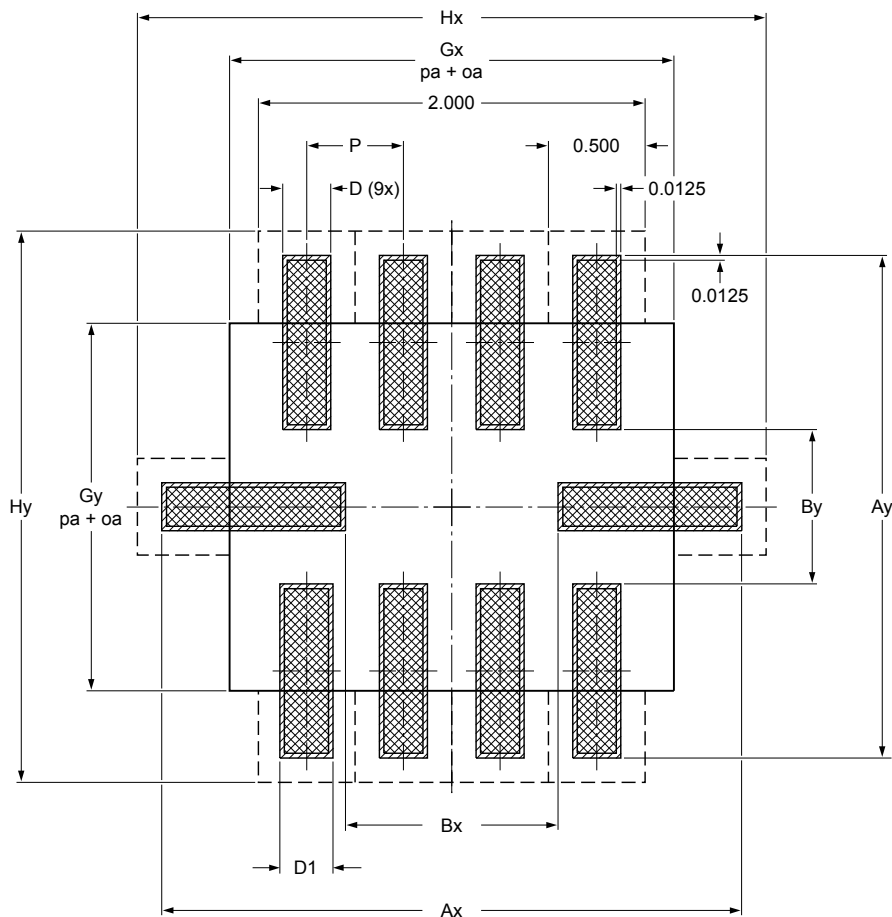
Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1049-3	---	MO255	---		40-12-06 11-03-30




**Fig. 1. Package outline XQFN10 (SOT1049-3)**

### 3. Soldering

Footprint information for reflow soldering of XQFN10 package

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-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- - - - - solder resist

DIMENSIONS in mm

P	Ax	Ay	Bx	By	D	D1	Gx	Gy	Hx	Hy
0.500	2.700	2.275	1.100	0.690	0.250	0.280	2.000	1.550	3.000	2.600

Issue date ~~12-06-14~~  
12-06-18

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Fig. 2. Reflow soldering footprint for XQFN10 (SOT1049-3)

## 4. Legal information

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